



QUALIFICATIONS VALIDATED  
ANNUALLY

QML-31032-1  
9 April 1997

**QUALIFIED MANUFACTURERS LIST**  
**OF**  
**DEPARTMENT OF DEFENSE PERFORMANCE SPECIFICATION**  
**MIL-PRF-31032**  
**PRINTED CIRCUIT BOARDS / PRINTED WIRING BOARDS**  
**GENERAL SPECIFICATION FOR**

This list has been prepared for use by or for the Government in the acquisition of printed circuit boards / printed wiring boards (hereafter referred to as printed boards) covered by Department of Defense Performance Specification MIL-PRF-31032. Listing of a manufacturer is not intended and does not connote endorsement of the manufacturer by the Department of Defense. All listings herein have been qualified under the requirements as specified in the latest effective issue of MIL-PRF-31032. This list is subject to change without notice; revision or amendment of this list will be issued as necessary. The listing of a manufacturer does not in any way release the manufacturer from compliance with the individual item specification requirements.

THE ACTIVITY RESPONSIBLE FOR THIS QML IS THE DEFENSE SUPPLY CENTER COLUMBUS (DSCC-VQ), COLUMBUS, OH 43216-5000.

If a manufacturer desires to have test data considered for qualification, it must be certified and meet all qualification test requirements of MIL-PRF-31032 and the applicable associated specification.

QML-31032 is available from the DSCC-VQ World Wide Web pages at the following addresses:

Web pages <http://www.dscclia.mil/V/VQ/index.html>

QML: <http://www.dscclia.mil/V/VQ/VQE/download/adobe/qml31032.pdf>: Adobe Acrobat PDF version.

QML is a definition of a manufacturer's verified capabilities. Manufacturers may use the add-on qualification process to qualify capabilities that are not currently listed on the QML. The user is encouraged to contact the manufacturer or DSCC to make arrangements for QML availability.

**SECTION I**

**LIST OF MANUFACTURERS BY ASSOCIATED SPECIFICATION**

**MIL-PRF-31032/1** -Printed Wiring Board, Rigid Multilayered, Woven E-Glass Reinforced Thermosetting Resin Base Material, With Plated Through Holes, For Soldered Part Mounting.

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Teradyne Circuits Operation  
4 Pittsburgh Avenue  
Nashua, New Hampshire 03060

Texas Instruments Inc.  
12501 Research Blvd. 78759  
Austin, TX 78714-9149

**MIL-PRF-31032/2** -Printed Wiring Board, Rigid, Single and Double Layer, Woven E-Glass Reinforced Thermosetting Resin Base Material, With or Without Plated Through Holes, For Soldered Part Mounting.

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Teradyne Circuits Operation  
4 Pittsburgh Avenue  
Nashua, New Hampshire 03060

Texas Instruments Inc.  
12501 Research Blvd. 78759  
Austin, TX 78714-9149

**SECTION II**

**LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

<b>MANUFACTURER NAME &amp; ADDRESS</b>  Teradyne Circuits Operation 4 Pittsburgh Avenue Nashua, New Hampshire 03060	<b>PLANT LOCATION</b>  Same	<b>CAGE CODE: 3T000</b>  <b>CONTACT: Lisa Greenleaf</b> <b>PHONE #: 603-791-3118</b> <b>FAX #: 603-791-3042</b> <b>EMAIL: greenleaf.lisa@tcs.teradyne.com</b>
<b>CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION:</b>		<b>QUALIFICATION LETTER:</b>
MIL-PRF-31032/1 MIL-PRF-31032/2  Panel Size                    24" X 36" Max. Board Thickness      0.322" Max/Min Hole Size        /0.016" Aspect Ratio                8:1 Max. Number of Layers    27 Min. Conductor Width     0.004" Min. Conductor Spacing   0.004" Part Mounting              THM, Compliant Pin, SMT Base Material  GF (Epoxy resin) GI (Polyimide resin) Finish System                Fused SnPB Nickel Gold Hole Preparation            Permanganate Desmear/Etchback Copper Plating               Acid Copper		VQE-97-0649 VQE-97-0721

**SECTION II (Continued)**

<b>MANUFACTURER</b>	<b>PLANT LOCATION</b>	<b>CAGE CODE: 96214</b>
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NAME & ADDRESS  Texas Instruments Inc. 12501 Research Blvd. 78759 Austin, TX 78714-9149	Same	CONTACT: Nanci Baggett PHONE #: (512) 250-6089 FAX #: (512) 250-7010 EMAIL: baggett@ti.com
CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION:	QUALIFICATION LETTER:	
MIL-PRF-31032/1 MIL-PRF-31032/2  Panel Size 18" X 24" Max. Board Thickness 0.150" Max/Min Hole Size /0.010" Aspect Ratio 9:1 Max. Number of Layers 20 Min. Conductor Width 0.004" Min. Conductor Spacing 0.004" Part Mounting THM, SM Base Material BI (Nonwoven aramid reinforced polyimide resin) GF (Epoxy resin) GI (Polyimide resin) Finish System Fused SnPB Hot Air Solder Leveling OSP Nickel Gold Hole Preparation Plasma Desmear/Etchback Copper Plating Acid Copper	VQE-97-0509 VQE-97-0718	

**SECTION III**

**ALPHABETICAL LIST OF QUALIFIED MANUFACTURERS**

MANUFACTURER	PLANT LOCATION	OTHER INFORMATION
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NAME & ADDRESS		
Teradyne Circuits Operation 4 Pittsburgh Avenue Nashua, New Hampshire 03060	Same	CAGE CODE: 3T000  CONTACT: Lisa Greenleaf PHONE #: 603-791-3118 FAX #: 603-791-3042 EMAIL: greenleaf.lisa@tcs.teradyne.com
Texas Instruments Inc. 12501 Research Blvd. 78759 Austin, TX 78714-9149	Same	CAGE CODE: 96214  CONTACT: Nanci Baggett PHONE #: (512) 250-6089 FAX #: (512) 250-7010 EMAIL: baggett@ti.com